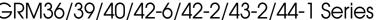
SURFACE MOUNT MONOLITHIC CHIP CAPACITORS COG AND TEMPERATURE COMPENSATING TYPES GRM36/39/40/42-6/42-2/43-2/44-1 Series





FEATURES

- Miniature size
- No Polarity
- Nickel Barrier Termination Standard highly resistant to metal migration
- Uniform dimensions and configuration
- Suitable for reflow soldering
- GRM39, 40 and 42-6 suitable for wave soldering
- Minimum series inductance
- Tape and Reel Packaging
- Bulk Case Packaging available for GRM40 and smaller
- Wide selection of capacitance values and voltages
- Largest production capacity and volume in the world

PART NUMBERING SYSTEM

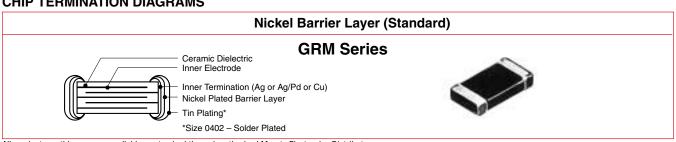
		GRM40	- COG 101 J	050 A	D 				
CAPACITOR TYPE AND SIZE See below and following pages.	3-digit code appears as necessary to indicate special thickness requirements.	TEMPERATURE CHARACTERISTICS COG COH P2H R2H S2H	CAPACITANCE VALUE Expressed in picofarads and identified by a three-digit number. First two digits represent significant figures. Last digit	CAPACITANCE TOLERANCE *= Standard ≤ 5pf: B = ±.1pf *C = ±.25pf >5pf to ≤10pf:	VOLTAGE Identified by a three-digit number.	MARKING A = Unmarked		PACKAGING	
							Reel Dian Tape Mat		Code
							7" Paper	Гаре	D
	Please consult	T2H U2J	specifies the number of zeros to follow.	B = ±.1pf			7" Plastic	Таре	L
	your local sales office	SL	For fractional values	C = ±.25pf *D = ±.5pf			13" Paper	Tape	J
	for details.		below 10pF, the letter "R"	>10pf:			13" Plasti	с Таре	K
			is used as the decimal point and the last digit becomes significant.	K = ±10% *J = ±5% G = ±2%			Bulk		В
							Bulk Casse	tte	С
			555571100 digititiounit.	F = ±1%			7" Paper 2mm pitch		Q
							See pages 115 packaging info		beling an

CHIP DIMENSIONS

Dimensions: mm	Size	EIA Code	L Length	W Width	T Thickness	e (min.) Termination	g (min.) Insulation
	GRM36	0402	1.0 ± 0.05	0.5 ± 0.05	0.5 ± 0.05	0.15 ~ 0.3	0.4
	GRM39*	0603	1.6 ± 0.1	0.8 ± 0.1	0.8 ± 0.1	0.2 ~ 0.5	0.5
		0805	2.0 ± 0.1	1.25 ± 0.1	0.6 ± 0.1	0.2 ~ 0.7	0.7
→ e g e -	GRM40				0.85 ± 0.1		
					1.25 ± 0.1		
	GRM42-6	1206	3.2 ± 0.15	1.6 ± 0.15	0.85 ± 0.1	0.3 ~ 0.8	1.5
			3.2 ± 0.13		1.15 ± 0.1		
			3.2 ± 0.2	1.6 ± 0.2	1.6 ± 0.2		
<u> </u>		GRM42-2 1210	3.2 ± 0.3	2.5 ± 0.2	1.15 ± 0.1	- 0.3 min.	1.0
 	GRM42-2				1.35 ± 0.15		
L W					1.8 ± 0.2		
					2.5 ± 0.2		
	GRM43-2	1812	4.5 ± 0.4	3.2 ± 0.3	2.0 max.	0.3 min.	2.0
	GRM44-1	2220	5.7 ± 0.4	5.0 ± 0.4	2.0 max.	0.3 min.	2.0

^{*}Bulk case packaging is L = 1.6 \pm 0.07, W, T = 0.8 \pm 0.07.

CHIP TERMINATION DIAGRAMS



All products on this page are available as standard through authorized Murata Electronics Distributors.

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SURFACE MOUNT MONOLITHIC CHIP CAPACITORS COG AND TEMPERATURE COMPENSATING TYPES — Instructor in Electronics SPECIFICATION GRM36/39/40/42-6/42-2/43-2/44-1 Series



GENERAL

Temperature Coefficient	Temperature Range			
COG = 0 ± 30 ppm*	-55° to +125°C			
$COH = 0 \pm 60 \text{ ppm}$	–55° to +125°C			
$P2H = N150 \pm 60 ppm$	–55° to +85°C			
$R2H = N220 \pm 60 \text{ ppm}$	–55° to +85°C			
$S2H = N330 \pm 60 ppm$	–55° to +85°C			
$T2H = N470 \pm 60 \text{ ppm}$	–55° to +85°C			
U2J = N750 ± 120 ppm	–55° to +85°C			
SL = N1000 to P350	–55° to +85°C			
*TC Tolerance for COG Refer to EIA-RS198E for other limitations				

ELECTRICAL

TEST			
Capacitance & Q (Frequency & Voltage):	≤1000pF 1MHz ± 100Hz @ 1.0 ± .2 Vrms >1000pF 1kHz ± 100Hz @ 1.0 ± .2 Vrms		
Q Limits	≤30pF: 400 + (20xC (pF)) >30pF: 1000 minimum		
Insulation Resistance (I.R.)	100,000 megohms or 1000 megohms – mfd (whichever is less) with rated voltage applied for 2 minutes max with 50mA limiting current		
Dielectric Strength (Flash)	250% of rated voltage for 5 seconds with series resistor limiting charging current to 50mA max.; 200% for 500V		
Aging	Negligible		

MECHANICAL

TEST	TEST METHOD	POST TEST LIMITS
Terminal Adhesion	Glass Epoxy Board	$\leq\!0603$ 1.0 lbs. $\geq\!0805$ 2.2 lbs. No evidence of termination peeling
Deflection	Mounting Capacitor R340 Load Deflection Unit: mm 45 45 Unit: mm Unit: mm Deflection Supporter	1 mm deflection (Glass epoxy board) No mechanical damage Cap., DF, IR meet initial limits
Solderability	MIL-STD-202 Method 208F	Contact factory for test limits

ENVIRONMENTAL

TEST	TEST METHOD	POST TEST LIMITS
Thermal Shock (Air to Air)	MIL-STD-202, Method 107, Condition A Post thermal Shock measurement shall be taken after 24 hours stabilization.	Appearance: No visual damage ΔC : = $\pm 2.0\%$ or ± 0.5 pF (whichever is greater) Q: >30 pF = $1,000$ min., ≤ 30 pF = $400 + [20 \times C(pF)]$ I.R.: = $100,000$ M Ω min. or $1,000$ M Ω • μ F (whichever is less)
Humidity, Steady State	Maintain the capacitor at $40 \pm 2^{\circ}$ C and 90 to 95% humidity for 500 ± 12 hours. Remove and let sit for 24 ± 2 hours at room temperature, then measure.	Appearance: No defects Capacitance: Within ±5% or ±.0.5pF (whichever is greater) Q/D.F.: 30pF and over: Q≥350; 10pf to 30pf: Q≥275+5/2C 10pf and below: Q≥200±10C I.R.: 1,000MΩ or 50MΩ F (whichever is less) C: Nominal Capacitance (pF)
Humidity Load	Apply the rated voltage at $40 \pm 2^{\circ}\text{C}$ and 90 to 95% humidity for 500 ± 12 hours. Remove and let sit for 24 ± 2 hours at room temperature, then measure. The charge/discharge current is less than 50mA .	Appearance: No defects Capacitance: Within $\pm 7.5\%$ or $\pm .0.75$ pF (whichever is greater) Q/D.F.: 30pF and over: Q ≥ 200 ; 30pf and below: Q $\ge 100\pm 10/3$ C I.R.: 500 M Ω or 25 M Ω F (whichever is less) C: Nominal Capacitance (pF)
Life Test	Apply 200% of rated voltage for 1000 ± 12 hours at maximum operating temperature; 150% for 500V. Upon completion of above test wait 24 hours prior to performing post testing.	Appearance: No defects Capacitance: $\pm 3\%$ or $\pm .3$ pF (whichever is greater) Q: >30 pF = 500 min., ≤ 30 pF = $200 + [10 \times C(pF)]$ I.R.: $1,000$ M Ω or 50 M Ω F (whichever is less) Flash: 250% rated voltage

STORAGE LIFE

Chip component terminations should generally be protected from moisture. In addition, they should also be protected from materials containing chlorine, sulfur compounds or any harmful gases that could cause degradation of the solder.

- 1. All chip components, including tape and reel, should be kept in an area where the temperature is between 5°C and 40°C and where the humidity is 20% to 70%.
- 2. The chip components should be used within six months.
- 3. The solderability of the chip components should be rechecked in the event that they are not used in six months.
- 4. Peel strength and shelf life of tape are guaranteed for 1 year when stored under afore said conditions.

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